

Program MSE  
MSE Day 18.11.2022



# **The Long and Winding Road:**

News from the Metadata Working Group

**Richard Thelen, KIT**

HELMHOLTZ

## Background

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- Till 2002: engineer at Siemens Electronic Assembly. Quality engineer for final product tests of PSGA.
- Since 2003: employee at IMT. MST, QM and metrology.

Some jobs:

1. Member of Prof. Hölscher group *Biomimetic Surfaces*
2. Responsible for two surface characterization labs at IMT
3. Technology expert for AFM within KNMF-i
4. PI for *Correlated Characterization* at IMT
5. MDMC member with focus on metrology issues
6. Vice chairman of DIN committee NA027-03-03
7. ...



# Outline

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- Team
- Idea
- Approach
- Processes described
- Issues
- Conclusion and Outlook

# The Team

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As the MDMC Metadata Working Group, we include:

- ERC
- FZJ
- KIT
- Hereon
- CNR-IOM

... and we are open to others!



# The Idea

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As a Metadata Working Group, we focus on:

- Ontologies
- Standardization
- FAIR Data
- Experimental workflows

to create the digital twin of real processes

# Approach

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How to start:

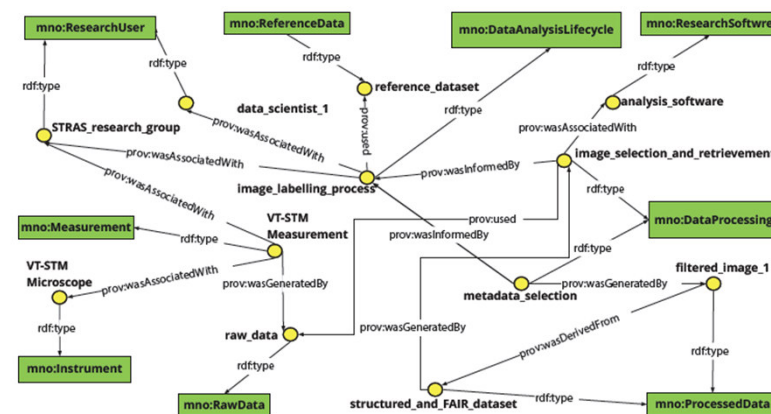
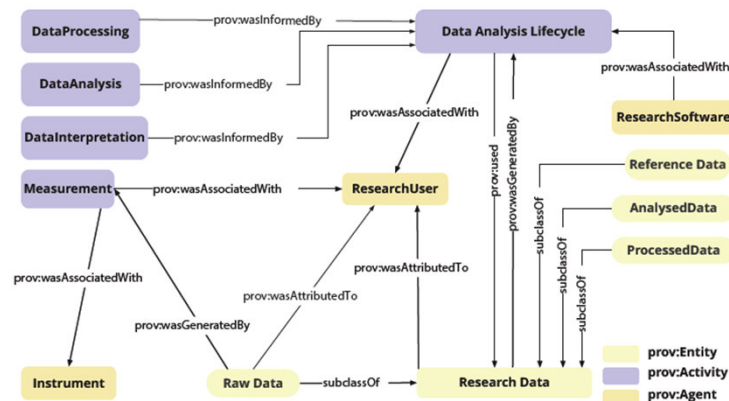
- Define common terminology
- Describe our individual processes
- Generate a model
- Feed it with real (meta)data
- Assess the results
- Draw conclusions



# Approach

Finding the Right Words ...

- MDMC-NEP Ontology developed and first application on STM:  
DOI: [10.5445/IR/1000152174](https://doi.org/10.5445/IR/1000152174)



- Cross check with NFFA, NFDI consortia, HMC, RDA, ...



NFDI4ing



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METADATA  
COLLABORATION



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# Approach

General Process Knowledge

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# Approach

Structuring present Process Knowledge

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## **Key Issue**

Describing generalized processes so that they fit to individual processes easily

## **Contradiction !**

Granularity used is fine enough to make individual process description straightforward

# Approach

Processes described

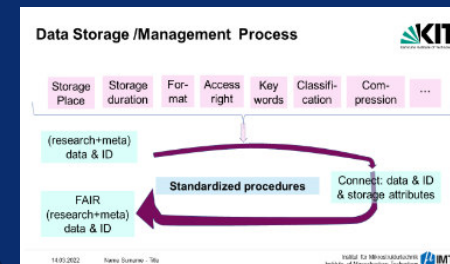
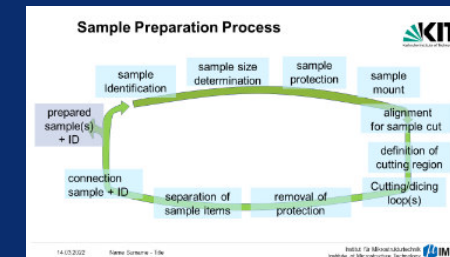
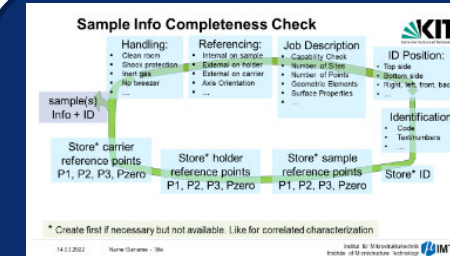
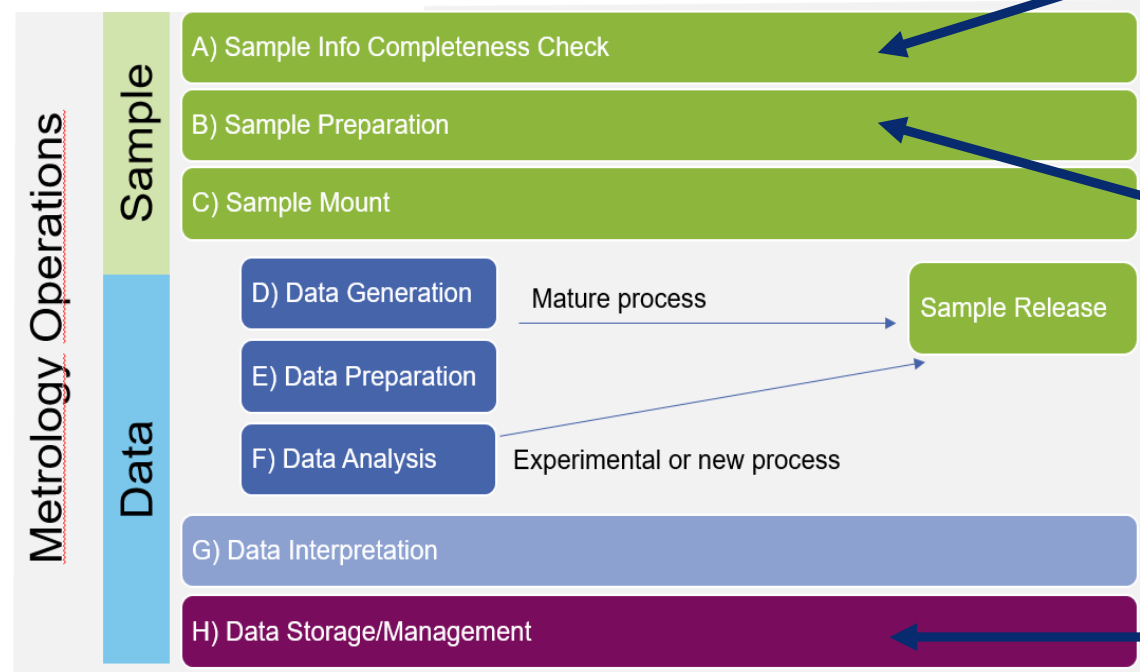
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- At KIT:           IMT, mainly metrology processes, now general manufacturing processes  
                          INT, mainly FIB, SEM and TEM
- At FZJ:           Ontology development
- At Hereon:       Cast based and powder based material development
- At CNR-IOM: FAIRification of STM process

# KIT Metrology Process

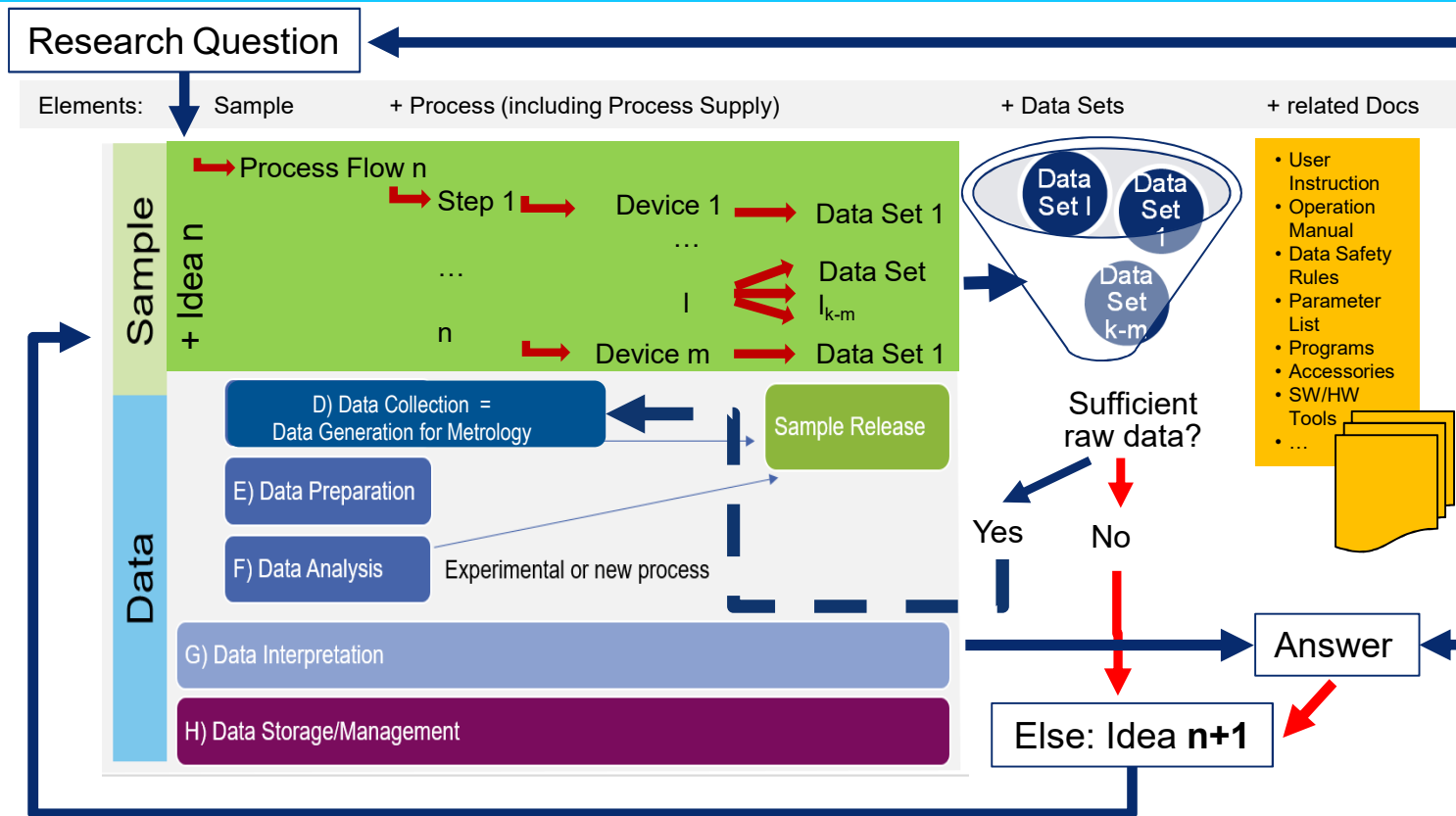
## Simplified Universal Metrology Process for Samples

Research Question → Answer



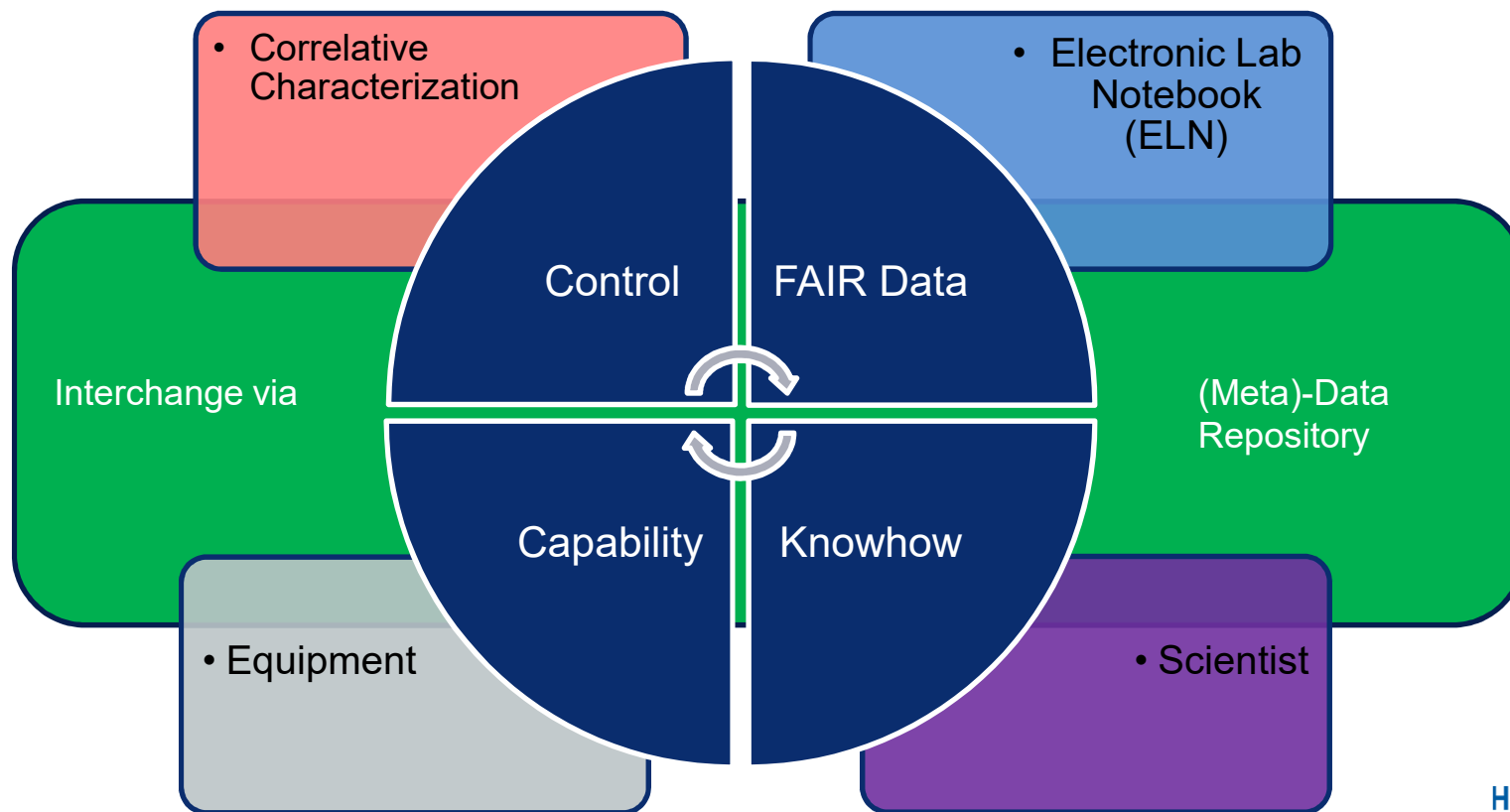
# KIT Manufacturing Process

## Simplified Universal Manufacturing Process for Samples



# KIT Manufacturing Process

To get a General Idea



# What an ELN should adress

Input from a Survey (a few future ELN Applicants, IMT only)

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ELNs are compatible. Data exchange to other systems possible (common standard).
Map process sequence via "Process card" and display next steps
Different users must be able to add information about a sample/process/project or new process steps easily on site.
How does version management work?
Quick and easy entry of process steps (e.g. using QR code)
Digital forms for process steps and samples. How to insert data from devices/systems?
Filtering by processes or parameters. Uniform tagging needed, link to ID number.
Link data sets (SEM, microscope, ...) automatically. As few clicks as possible for data backup. FAIR storage of secondary information
Browser-based (thus openly accessible on all OS)
Sign off process steps by authorized person (compare signature and date in processing card)
Project mapping (background info on sample, accompanying documents "goods in / goods out")
Automatic time-of-use recording
Automatic mails to next processor
Integration of FAQs, manual, possibly learning videos for basics, device-specific
Guest account with few queries/simple "manual" data entry at facility/device.
Bundling of user data and simplified user administration as additional task



# KIT Manufacturing Process

From Simple Process Flow to ELN



		<b>Laufkarte</b> <b>HFE</b>	<b>602</b>	
<b>Losnummer: 04552</b>		<b>Grüne Laufkarte</b>		
<b>IFA-Nummer:</b> 11-935F-01F <b>Erzeugnisnummer:</b> entfällt <b>Auftraggeber:</b> Nees		<b>Beistellteile, Masken etc:</b> Siehe FS02	<b>Fertigungsgegenstand:</b> HFE für Röntgenzwischenmasken	
lfd.-Nr.	Fertigungsablauf	Vorgaben (z.B. AA, PA, SP, Text, Anlagen etc.)	Anzahl ein aus	Erledigt Name, Datum
1.	Laufkarte erstellen und Laufordner anlegen.	AA605.xx	---	(MF-FVB)
2.	Laufkarte und ggf. Beistellteil(e) übernehmen.	AA605.xx		(GL-FAF)
3.	Substrate vom Typ <b>SP403009.xx</b> entsprechend der Losgröße (max 4) mit den Los-Nummern: 1.) Los-Nr.: ..... 2.) Los-Nr.: ..... 3.) Los-Nr.: ..... 4.) Los-Nr.: ..... dem Reinraumlager entnehmen und Waferbox kennzeichnen	AA619.xx Klebeetiketten beige stellt	4	
4.	Metallisierungsschicht aufdampfen	AA653.xx Cr-Dicke: 5nm Au-Dicke: 15nm		
5.	Waferbox des gefertigten HFE Losnummer und Temperbedingungen versehen und im Reinraum-Lager VB6 einlagern	AA610.xx		
6.	Laufordner an MF-FVB zurückgeben.	AA605.xx		
7.	Ende des Laufkartenumlaufes in der Liste LI405.00_Losnummern dokumentieren.		---	(MF-FVB)
8.	Laufkarte und Laufordner auf Vollständigkeit prüfen. <input type="checkbox"/> Laufordner an Auftraggeber aushändigen <input type="checkbox"/> Laufordner bei MF-FVB archivieren	AA605.xx	---	(MF-FVB)

Lars Griem, IAM

Martin Starmann, IBCS

What else

- Specifications
- Standard Operating Procedures
- User Instructions
- Safety Data Sheets
- Manuals
- Training Docs
- Custom Tools
- Automation Programs
- Custom Carrier
- Device Maintenance Plan
- ...

**Total: >80 pages for a simple 3 step process**

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## Issues addressed at KIT



### Common Mechanical Interface

- Challenge: not available for many Devices
- Solution: 3D printed Interposers for quick Adaptation



### Meta Data Collection

- Challenge: some Devices have no Meta Data available
- Solution: Custom SW to read Windows Handles



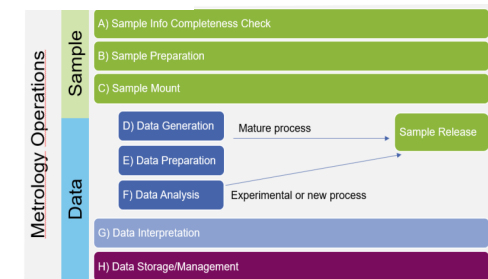
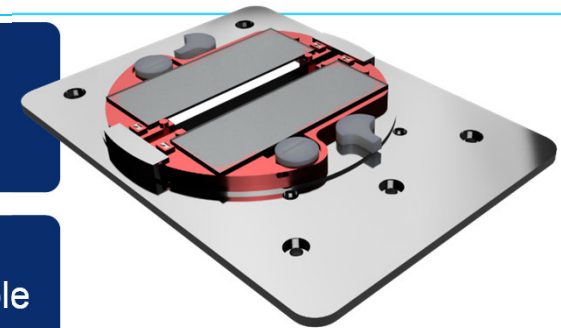
### Network Connection

- Challenge: Standard is shifted from IPv4 to IPv6
- Solution: SCC Support to migrate Devices







### Universal Metrology Process Description

- Challenge: versatile but detailed Description
- Solution: Process Flow developed within MDMC



## Issues to be addressed ...

... by Helmholtz and beyond

	<p>Operating System Software Maintenance</p> <ul style="list-style-type: none"><li>• Challenge: Device SW Upgrade not synchronized</li><li>• Solution: <input type="text"/></li></ul>
	<p>Transfer Process Knowledge from User to ELN</p> <ul style="list-style-type: none"><li>• Challenge: Hundreds of Steps, individual Knowhow, little Resources</li><li>• Solution: <input type="text"/></li></ul>
	<p>Standardized PIN Generator</p> <ul style="list-style-type: none"><li>• Challenge: Diverse Requirements</li><li>• Solution: <input type="text"/></li></ul>
	<p>Standardized Process Description</p> <ul style="list-style-type: none"><li>• Challenge: Who is defining the „Standard“</li><li>• Solution: <input type="text"/></li></ul>

?

## Top Five Issues

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1. Commitment that Infrastructure Development **is** Scientific Work. Even without any Publication.
2. Clever Strategy to separate Relevant Data from Total Data without Information Overflow
3. Protection of Knowledge/IP, secured Data Exchange
4. Local Resources for the Lab specific ELN Setup
5. Money to run Infrastructure beyond next POF Evaluation

# Resume'

## Pros

- Automation supports Reproducible Results
- Documentation Standards to search for Experiments
- More Time for Trials
- Knowledge Base for AI

## Cons

- Forced to stay with SW (see Windows)
- High Level of Maintenance for HW/SW
- Efficiency  $\neq$  Scientific Quality
- Total Transparency: Dream ... or Nightmare

# Outlook

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- We are getting closer
- We will go on
- We might accelerate
- We should



Use coin to rub gently.

Avoid waste. Help to make the world a better place.

Scientists are liable for dreams that don't come true due to misuse, lack of productivity, delay or any other shortcomings related to individual scientific work.



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The End